

SID

Factory: Rot am See

Article:

453

ML4

Provided:

Kracht, Enrico

Customer:

Date:

17.04.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
---------------	----------	----	---------	------------------

A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	A00 B00
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	360		2	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		3	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		4	
B-RS-FR4-DS-1.55mm-018+018-TG150-HF	50200661	18	L2		
		1514		5	
		18	L3		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	360		6	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		7	
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	0		8	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	9	

Thickness after Pressing

B00:

2290 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2530 µm

Dmin:

2050 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2400 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2640 µm

Dmin:

2160 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

2306 µm

Version 1.2.14.15

© Würth Elektronik